

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	ANALOG MEMS SENSORS/25/15589
1.3 Title of PCN	ST Manufacturing Reshaping (Analog_HC7_CR200toRST8_All): Qualification of RST8 (France) as new FE Location.
1.4 Product Category	Please refer to the impacted Products List in HC7 Technology.
1.5 Issue date	2025-07-23

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	PIKE EMMA
2.1.2 Phone	+44 1628896111
2.1.3 Email	emma.pike@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Marcello SAN BIAGIO
2.1.2 Marketing Manager	Lionel GRILLO
2.1.3 Quality Manager	David MOCELLIN

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Manufacturing reshaping program	Manufacturing reshaping program	RTS8 (France)

4. Description of change

	Old	New
4.1 Description	CR200 (France) as FE Plant	RST8 (France) as FE plant
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impact. The products guarantee the same quality and electrical characteristics as per current production.	

5. Reason / motivation for change

5.1 Motivation	In the frame of ST manufacturing reshaping program (refer to Corporate PCI 15383 - Early Notification), following the continuous improvement of our service and to increase production Capacity, ST Microelectronics is announcing the qualification of RTS8 (France) as FE Location for the impacted Products in HC7 Technology. Please note that for products with PIX (polyimide at top passivation), production flow until PIX deposition will be done in ST Rousset, and the step of PIX deposition will be moved to ST Singapore. And on top of Front end transfer, the backgrinding of the wafer (to reach final die thickness) will be performed in ST Bouskoura (instead of ST Rousset) for selected products. We will also implement a change in a component of glue ablestick 8601-S25 to become PFAS free. For selected products in SO8, we will also implement a second source for back end production in TSHT (china). And for TSSOP14 and TSSOP16 packages, we will also transfer the back end production to a new plant. All details are listed in the attachment. Please be advised that the enclosed list of products and dates could be subject to change. Such modifications may occur as part of the ongoing transformation program and will be communicated as and when available.
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	Traceability of change will be ensured by an internal codification (Finished Good/Type) printed on the carton box label.
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7. Timing / schedule

7.1 Date of qualification results	2027-01-15
7.2 Intended start of delivery	2027-07-15
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)			
15589 Public product.pdf 15589 Qualification Plan HCMOS7 (3).zip			

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STG3682QTR	
	STG3692QTR	

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